



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: A8250

Philip Joseph KOH

Appln. No.: 09/998,241

Group Art Unit: 2811

Confirmation No.: 6210

Examiner: Ori NADAV

Filed: December 03, 2001

For: HIGH FREQUENCY LOW COST PACKAGE FOR SEMICONDUCTOR DEVICES

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated November 26, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please enter the following amended claims:

34. (Amended) A method of making a dielectric package for housing a component and having an integral connection component comprising:

providing a first die, said first die having an integral planar connection member and having at least one conductor patterned on said first die;

providing a second die having at least one conductor patterned on said second die; and

bonding said second die to said first die such that the conductor on said first die is aligned with said conductor on said second die and said integral connection member on said first die forms a planar connection component for said dielectric package.

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